

SOT758-1

HVQFN16; plastic, thermal enhanced very thin quad flatpack; no leads; 16 terminals; 0.5 mm pitch; 3 mm x 3 mm x 0.85 mm body

29 September 2025

Package information



1 Package summary

Terminal position code	Q (quad)
Package type descriptive code	HVQFN16
Package type industry code	HVQFN16
Package style descriptive code	HVQFN (thermal enhanced very thin quad flatpack; no leads)
Package body material type	P (plastic)
JEDEC package outline code	MO-220
Mounting method type	S (surface mount)
Issue date	21-10-2002

Table 1. Package summary

Parameter	Min	Nom	Max	Unit
package length	2.9	3	3.1	mm
package width	2.9	3	3.1	mm
seated height	-	0.85	1	mm
package height	-	0.85	-	mm
nominal pitch	-	0.5	-	mm
actual quantity of termination	-	16	-	

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2 Package outline

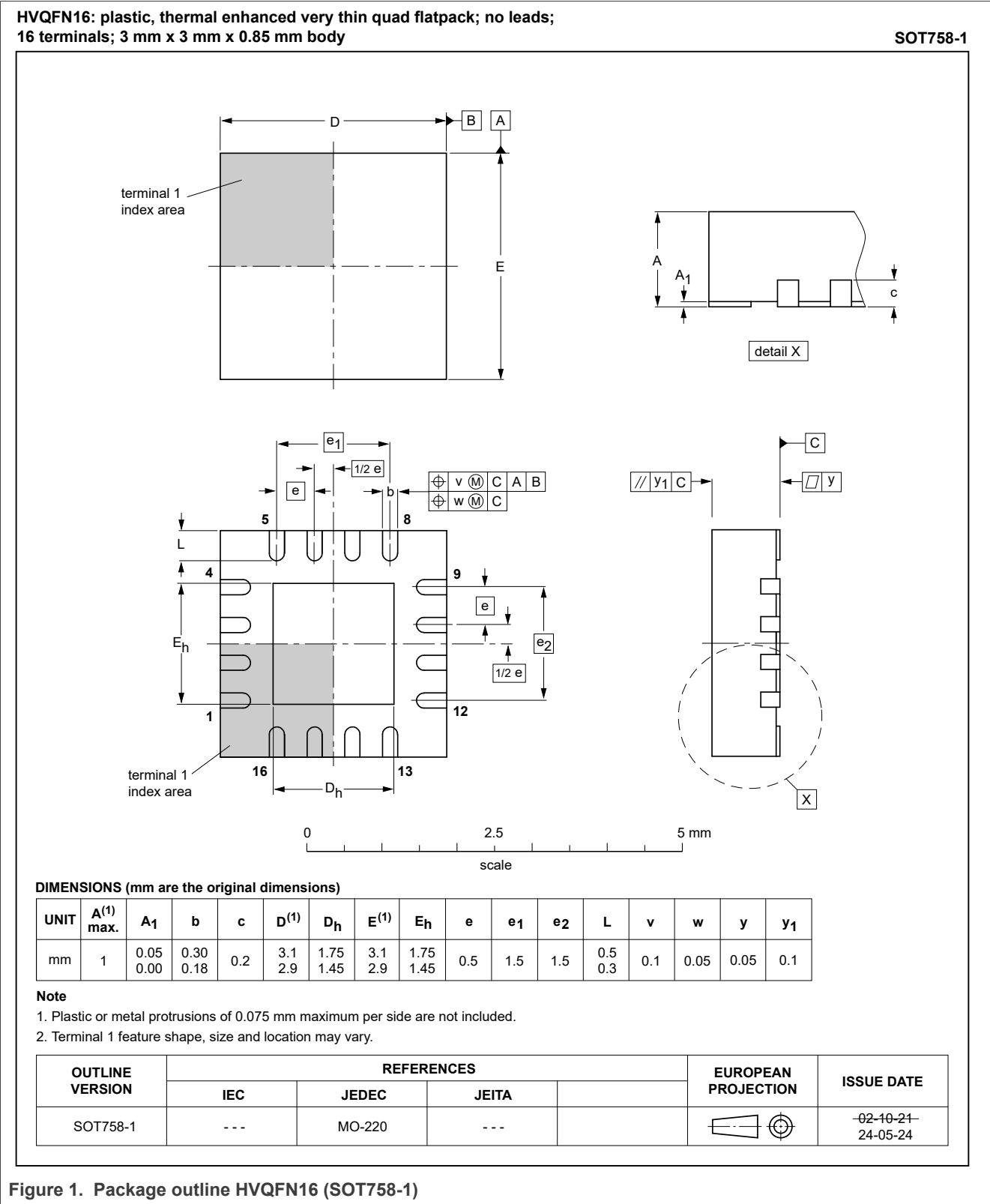


Figure 1. Package outline HVQFN16 (SOT758-1)

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3 Soldering

Footprint information for reflow soldering of HVQFN16 package SOT758-1

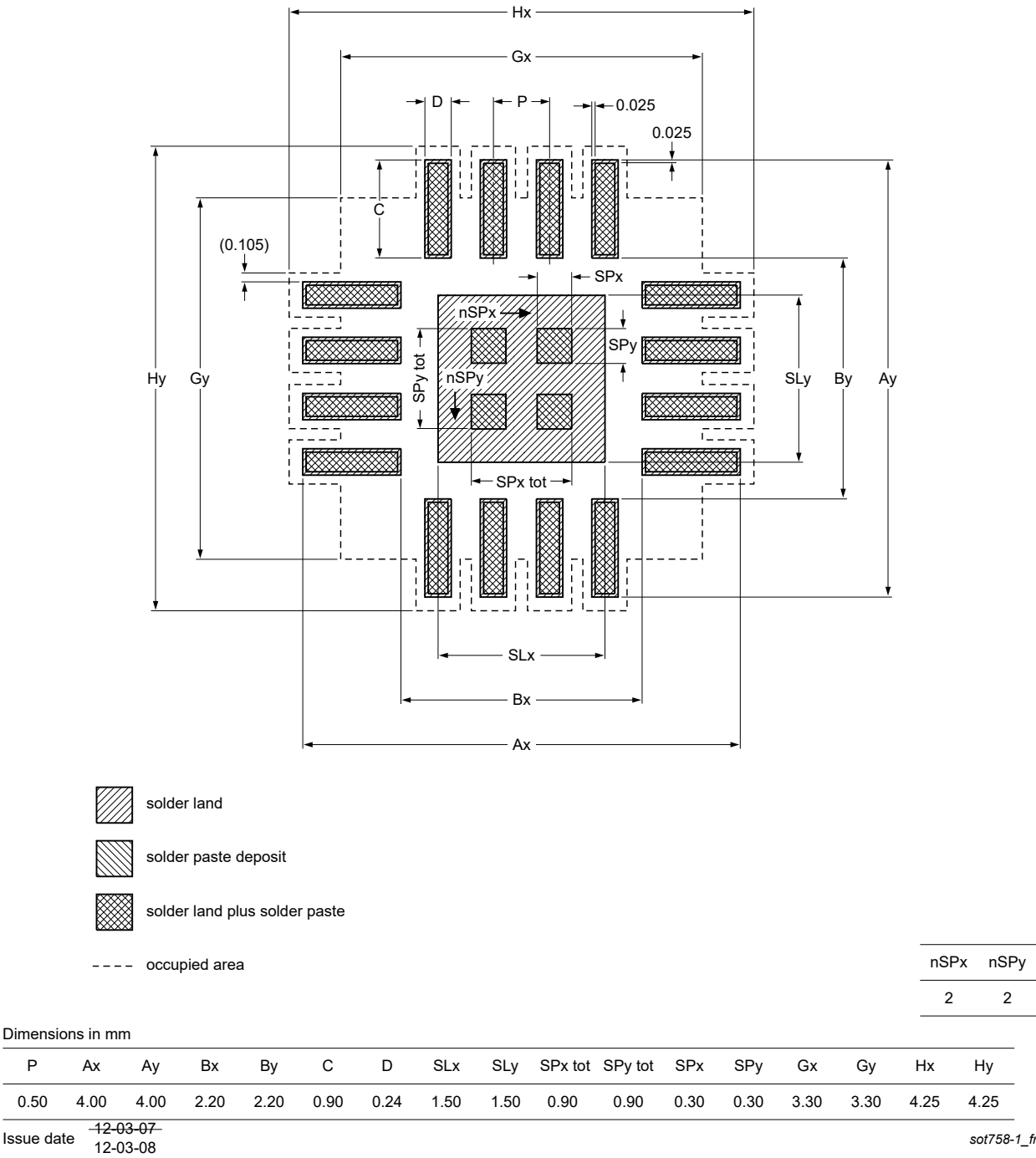


Figure 2. Reflow soldering footprint for HVQFN16 (SOT758-1)

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4 Legal information

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